

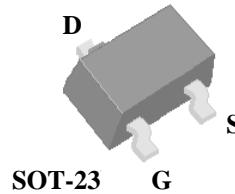
XP10TN135N

Halogen-Free Product



**N-CHANNEL ENHANCEMENT MODE
POWER MOSFET**

- ▼ Simple Drive Requirement
- ▼ Fast Switching Characteristic
- ▼ Low Gate Charge
- ▼ RoHS Compliant & Halogen-Free

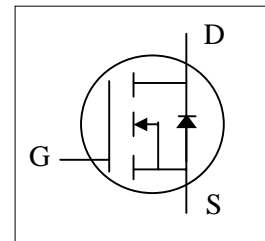


BV_{DSS}	100V
$R_{DS(ON)}$	135m Ω
I_D	3A

Description

XP10TN135 series are innovative design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The special design SOT-23 package with good thermal performance is widely preferred for all commercial-industrial surface mount applications using infrared reflow technique and suited for voltage conversion or switch applications.



Absolute Maximum Ratings @ $T_J=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_C=25^\circ\text{C}$	Drain Current, $V_{GS} @ 10\text{V}$	3	A
$I_D @ T_A=25^\circ\text{C}$	Drain Current, $V_{GS} @ 10\text{V}^3$	2.1	A
$I_D @ T_A=70^\circ\text{C}$	Drain Current, $V_{GS} @ 10\text{V}^3$	1.7	A
I_{DM}	Pulsed Drain Current ¹	10	A
$P_D @ T_A=25^\circ\text{C}$	Total Power Dissipation	1.38	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-c	Maximum Thermal Resistance, Junction-case	45	$^\circ\text{C}/\text{W}$
Rthj-a	Maximum Thermal Resistance, Junction-ambient ³	90	$^\circ\text{C}/\text{W}$

Electrical Characteristics @T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	100	-	-	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =2A	-	112	135	mΩ
		V _{GS} =4.5V, I _D =1A	-	120	145	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	1.7	3	V
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =2A	-	8	-	S
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V, V _{GS} =0V	-	-	25	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Q _g	Total Gate Charge	I _D =2A	-	12	20	nC
Q _{gs}	Gate-Source Charge	V _{DS} =80V	-	2.2	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =10V	-	2.5	-	nC
t _{d(on)}	Turn-on Delay Time	V _{DS} =50V	-	7	-	ns
t _r	Rise Time	I _D =1A	-	5	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =3.3Ω	-	16	-	ns
t _f	Fall Time	V _{GS} =10V	-	6	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	610	980	pF
C _{oss}	Output Capacitance	V _{DS} =25V	-	40	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	25	-	pF
R _g	Gate Resistance	f=1.0MHz	-	2.2	4.4	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{SD}	Forward On Voltage ²	I _S =1.2A, V _{GS} =0V	-	-	1.2	V
t _{rr}	Reverse Recovery Time	I _S =2A, V _{GS} =0V,	-	21	-	ns
Q _{rr}	Reverse Recovery Charge	dI/dt=100A/μs	-	21	-	nC

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in² copper pad of FR4 board, t ≤10sec ; 270 °C/W when mounted on Min. copper pad.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

XSEMI DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT

DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

XSEMI RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.

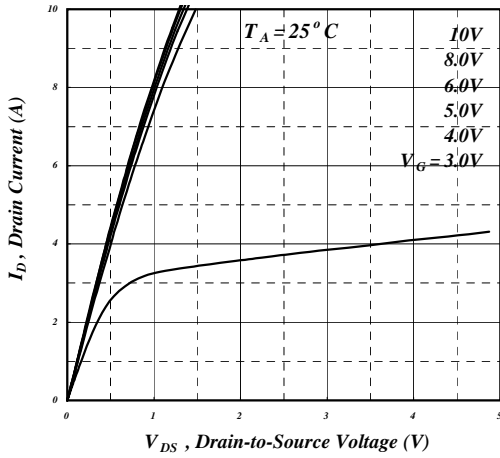


Fig 1. Typical Output Characteristics

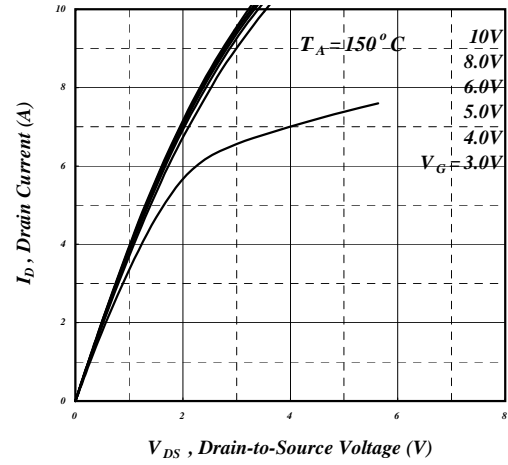


Fig 2. Typical Output Characteristics

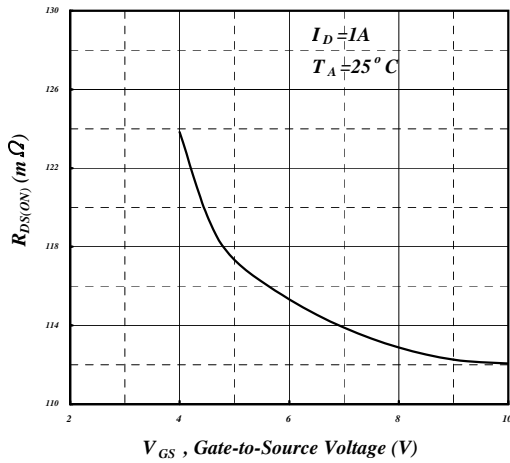


Fig 3. On-Resistance v.s. Gate Voltage

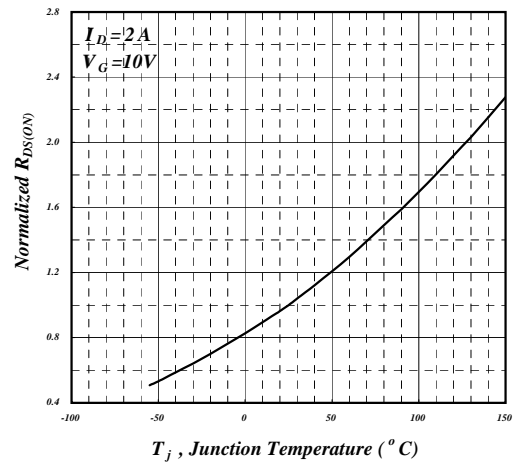


Fig 4. Normalized On-Resistance v.s. Junction Temperature

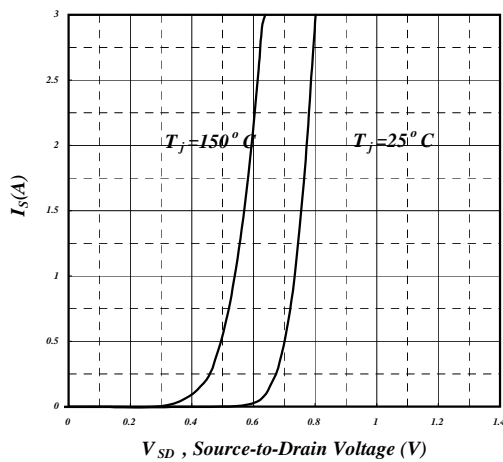


Fig 5. Forward Characteristic of Reverse Diode

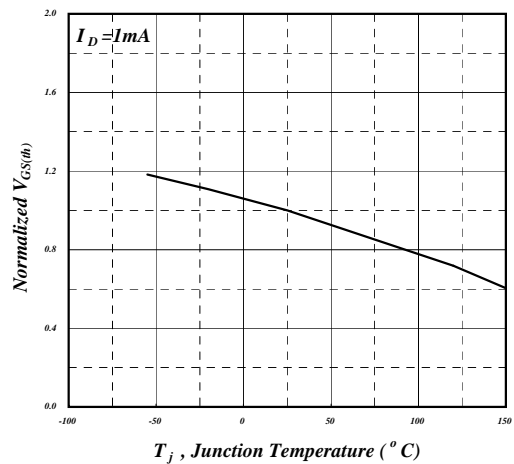


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

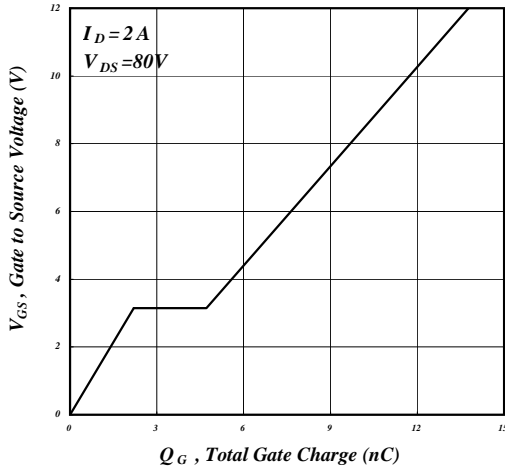


Fig 7. Gate Charge Characteristics

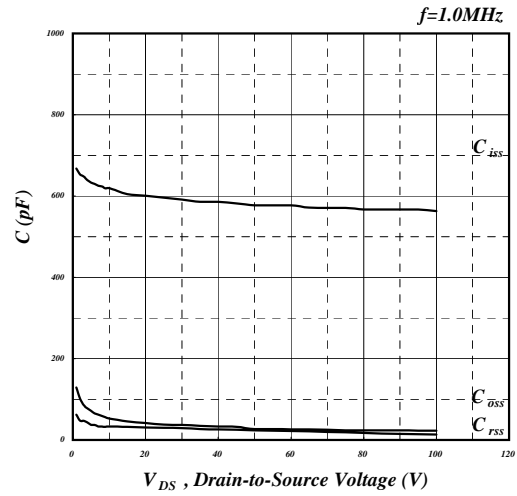


Fig 8. Typical Capacitance Characteristics

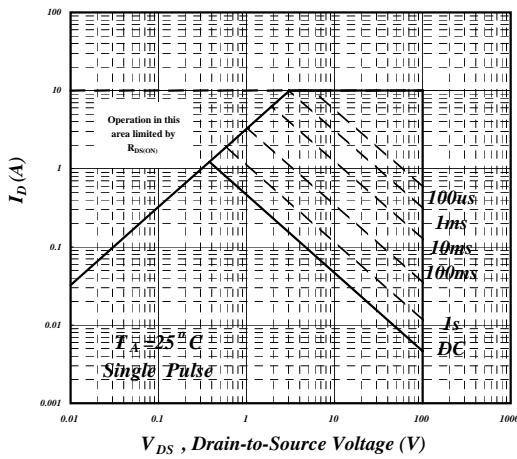


Fig 9. Maximum Safe Operating Area

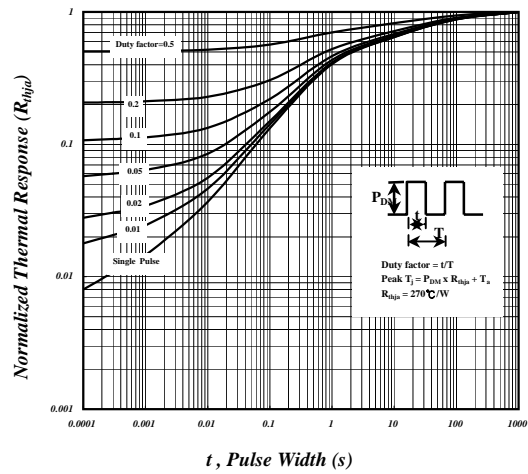


Fig 10. Effective Transient Thermal Impedance

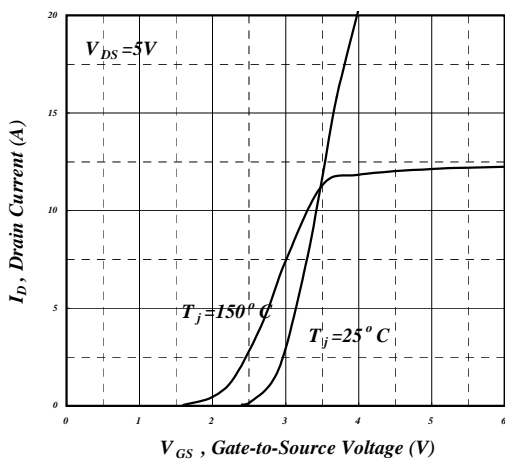


Fig 11. Transfer Characteristics

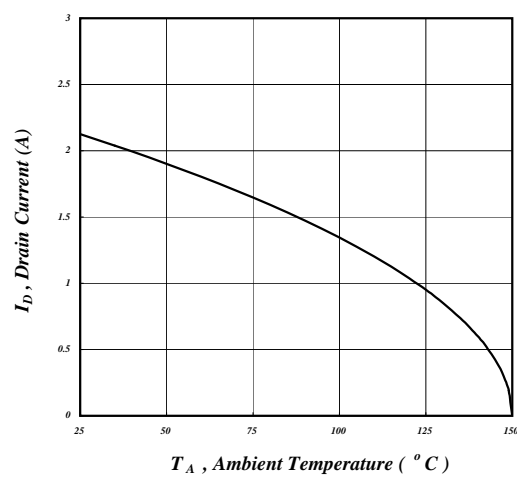


Fig 12. Drain Current v.s. Ambient Temperature

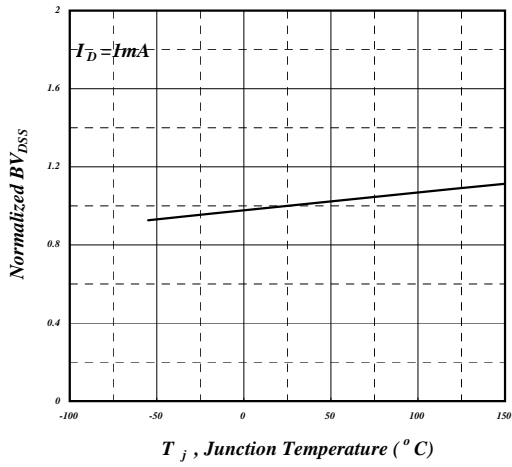


Fig 13. Normalized BV_{DSS} v.s. Junction Temperature

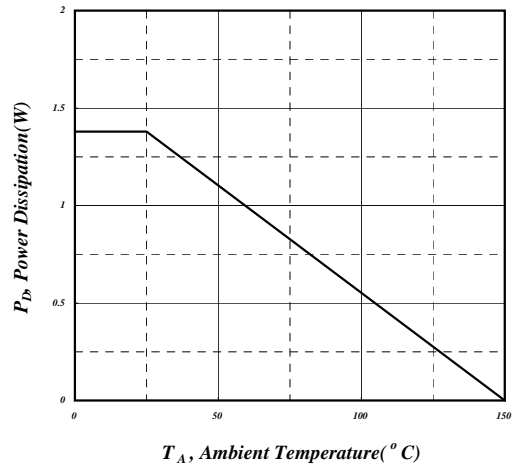


Fig 14. Total Power Dissipation

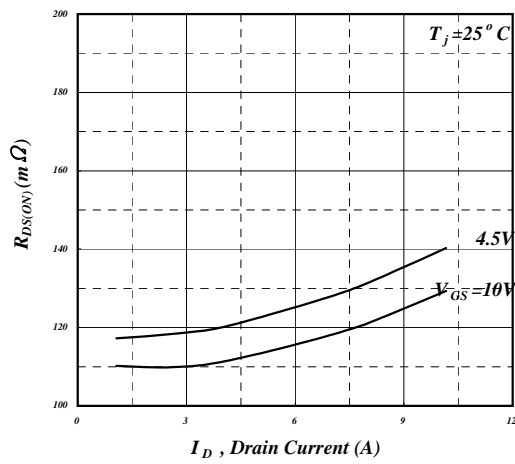


Fig 15. Typ. Drain-Source on State Resistance

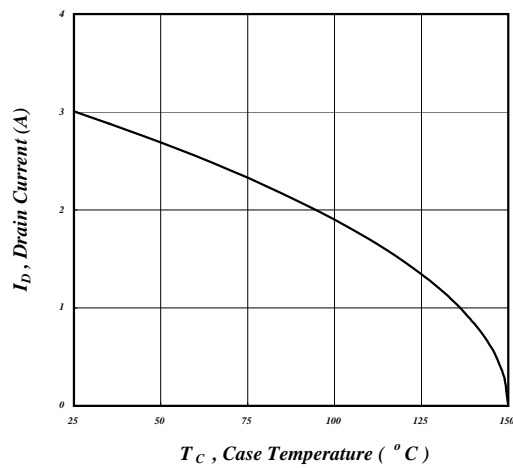


Fig 16. Drain Current v.s. Case Temperature